



INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

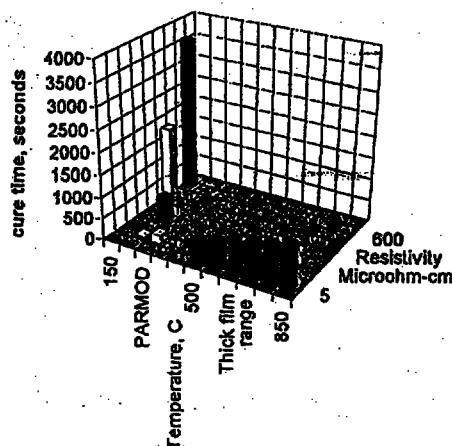
(51) International Patent Classification ⁶ : C08K 3/08, C08L 23/26, B05D 1/32, 5/12		A1	(11) International Publication Number: WO 98/37133
			(43) International Publication Date: 27 August 1998 (27.08.98)
(21) International Application Number: PCT/US97/16226		(74) Agents: WOODBRIDGE, Richard, C. et al.; Woodbridge & Associates, P.C., P.O. Box 592, Princeton, NJ 08542-0592 (US).	
(22) International Filing Date: 12 September 1997 (12.09.97)			
(30) Priority Data:		(81) Designated States: AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, CA, CH, CN, CU, CZ, DE, DK, EE, ES, FI, GB, GE, HU, IL, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MD, MG, MK, MN, MW, MX, NO, NZ, PL, PT, RO, RU, SD, SE, SG, SI, SK, TJ, TM, TR, TT, UA, UG, US, UZ, VN, ARIPO patent (GH, KE, LS, MW, SD, SZ, UG, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, CH, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, ML, MR, NE, SN, TD, TG).	
① 60/038,669 / 20 February 1997 (20.02.97) US ② 60/038,514 / 20 February 1997 (20.02.97) US ③ 60/038,670 / 20 February 1997 (20.02.97) US ④ 60/038,453 / 20 February 1997 (20.02.97) US ⑤ 60/046,552 / 15 May 1997 (15.05.97) US ⑥ 60/046,541 / 15 May 1997 (15.05.97) US ⑦ 60/046,540 / 15 May 1997 (15.05.97) US			
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(54) Title: LOW TEMPERATURE METHOD AND COMPOSITIONS FOR PRODUCING ELECTRICAL CONDUCTORS

(57) Abstract

A composition for matter having a metal powder or powders for specified characteristics in a Reactive Organic Medium (ROM). These compositions can be applied by any convenient printing process to produce patterns of electrical conductors on temperature-sensitive electronic substrates. The patterns can be thermally cured in seconds to form pure metal conductors at a temperature low enough to avoid damaging the substrate.

Thick Film On Polymer Alternatives



	Electrical Resistivity Microhm-cm	Temperature C	Cure time minutes
Carbon-epoxy	>500	150	30-90
Silver-epoxy	>50	150	30-90
Transient Liquid Phase	30-40	220	>10
PARMOD	<6	220-360	<3
Conventional thick film	<6	500-850	>10